

METHOD AND STRUCTURE OF A SUBSTRATE WITH BUILT-IN VIA-HOLE RESISTORS

ABSTRACT OF THE DISCLOSURE

A structure and a method of a substrate with built-in via hole resistors are disclosed. The substrate structure includes a core layer made of insulating material and a plurality of via holes for filling with polymer thick film resistor. After the via holes are filled with PTFR, a solder ball or a pad is formed on both ends of the via hole to provide electrical conductivity.